

In the Claims:

Claim 1 (currently amended): A structure comprising:

- a laminate substrate having a top surface for receiving a semiconductor die;
- an antenna situated on a bottom surface of said laminate substrate, said antenna being suitable for connection to said semiconductor die;
- a laminate substrate reference pad in said laminate substrate, said laminate substrate reference pad situated over said antenna;
- at least one laminate substrate reference via situated at a side of said antenna, said at least one laminate substrate reference via being electrically connected to said laminate substrate reference pad.

Claim 2 (original): The structure of claim 1 wherein said laminate substrate reference pad is a laminate substrate ground pad.

Claim 3 (original): The structure of claim 1 wherein said at least one laminate substrate reference via is a laminate substrate ground via.

Claim 4 (canceled).

Claim 5 (original): The structure of claim 1 wherein said at least one laminate substrate reference via is electrically connected to a printed circuit board reference via in a printed circuit board.

Claim 6 (original): The structure of claim 5 wherein said printed circuit board reference via is connected to a printed circuit board reference pad.

Claim 7 (original): The structure of claim 1 wherein said laminate substrate comprises an organic material.

Claim 8 (original): The structure of claim 1 wherein said laminate substrate comprises a ceramic material.

Claim 9 (previously presented): The structure of claim 1 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.

Claim 10 (original): The structure of claim 1 wherein said at least one laminate substrate reference via is electrically connected to a laminate substrate ball pad on said bottom surface of said laminate substrate.

Claim 11 (currently amended): A structure comprising:

a laminate substrate having a top surface for receiving a semiconductor die;

an antenna situated on a bottom surface of said laminate substrate, said antenna being suitable for connection to said semiconductor die;

a laminate substrate reference pad in said laminate substrate, said laminate substrate reference pad situated over said antenna;

a plurality of laminate substrate reference vias, each of said plurality of laminate substrate reference vias situated at a side of said antenna, said each of said plurality of laminate substrate reference vias being electrically connected to said laminate substrate reference pad.

Claim 12 (original): The structure of claim 11 wherein said laminate substrate reference pad is a laminate substrate ground pad.

Claim 13 (original): The structure of claim 11 wherein said each of said plurality of laminate substrate reference vias is a laminate substrate ground via.

Claim 14 (canceled).

Claim 15 (original): The structure of claim 11 wherein said each of said plurality of laminate substrate reference vias is electrically connected to a respective one of a plurality of printed circuit board reference vias in a printed circuit board.

Claim 16 (original): The structure of claim 15 wherein each of said plurality of printed circuit board reference vias is electrically connected to a printed circuit board reference pad.

Claim 17 (original): The structure of claim 11 wherein said laminate substrate comprises an organic material.

Claim 18 (original): The structure of claim 11 wherein said laminate substrate comprises a ceramic material.

Claim 19 (previously presented): The structure of claim 11 wherein a shape of said antenna is selected from the group consisting of a square shape, a rectangular shape, a slot line pattern, a meander line pattern, and a patch pattern.

Claim 20 (original): The structure of claim 11 wherein said each of said laminate substrate reference vias is electrically connected to a respective one of a plurality of laminate substrate ball pads on said bottom surface of said laminate substrate.